DESY MMC V1.0

Standardized Solution of Management Controller for MTCA.4

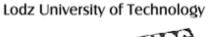
Michael Fenner, Dariusz Makowski

Progress on MMC V1.00 Management Controller for MTCA.4 Hamburg, 11.12.2014













Introduction

- > Agenda:
 - Repetition of MMC features
 - Improvements in 2014
 - Demonstration
- DESY MMC V1.0 is a set of hardware and software building blocks, created by DESY and its partners
- Management is the most difficult part, almost all interoperability issues are based on management
- Idea: Create one proven feature-rich standard solution and share it with the partners
- Bases on Atmel ATxmega128A1
- Over 5 man-years of design work put into it
- Great improvements during the last year

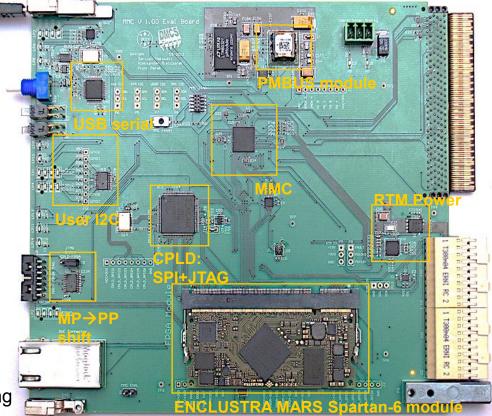




Overview of Building Blocks – Starter Kit

Commonly used Blocks

- IPMI Communication
 - Intensively tested with NAT and Vadatech
- Power Management
 - Sequencing and safety shutdown
- FPGA Management
 - DONE, INIT, PROG, RESET over IPMI
- > HPM.1 MMC and FPGA upgrade
 - Redundant SPI Flashes
- RTM Management
 - RTM Inrush current control
 - Temperature, voltage and current monitoring



Design: Dariusz Makowski, DMCS

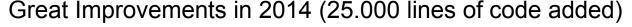
- CPLD for JTAG and Flash Control (optional!)
 - Allows to program "dead board"; Redundant Flash selection
- > Debug UART
- PMBUS control



Progress

State of Last Year: "Basic" functionality (Development Version)

- IPMI Communication
- Power Management, Temperature Monitoring
- FPGA Management
- Static CPLD for JTAG and Flash Control
- > AMC FRU generator



- Architecture change: Full separation IPMI/user logic
- Vadatech compatibility: IW25, IW26
- > HPM.1 Support (8KB Boot loader) → MMC, SPI
- MMC and CPLD register control with IPMItool
- Temperature Events (Fan speed increase)
- Automation tools (program.bat, bin2hpm)











Reference Customers

- DESY MMC V1.00 is running on DESY Boards
 - DAMC-FMC20, DAMC-FMC25, DAMC-TCK7
- In 2014 we won partners very good feedback
 - CAENels
 - Michigan State University
 - NRF Korea
 - Micro-Research Finland
 - Interface Concept
 - In negotiation with SLAC
- Success story: Struck SIS8300L2
 - Spend two days together for MMC schematic change
 - Spend one day for Code-Porting
 - Full set of new features: Remote MMC and Flash Upgrade, redundant FPGA Flash Memories, RTM inrush current control, Temperature Alerts, FPGA and RTM supervision







Micro-Research Finland Oy







Demonstration

- > Sensor Information
- > HPM file generation
- > IPMI Upgrade
- > Production Programming



Bin2hpm – in Bitfile mode

```
D:bin2hpm llrf_ctrl_sis83001_acc1_r908.bit /bit /compress
BIN-to-HPM file converter. Version: 1.0
Written by Michael Fenner (C) DESY 2014;
with compression based on VPackBits (C) Michael Dipperstein (LGPL) and
with MD5 algorithm from Alexander Peslyak (public domain)
Reading file
                                  : 11rf_ctrl_sis83001_acc1_r908.bit
File Lengh is
                                  : 5465076 bytes
Bit File mode. Header check ok.
a-Section detected. Design info : ENT_SIS8300L_TOP.ncd;UserID=0xFFFFFFFF
b-Section detected. Part name
                                  : 6vlx130tff1156
                                  : 2014/11/27
c-Section detected. File date
d-Section detected. File time
                                  : 01:58:26
e-Section detected. Image size
                                  : 0x0053638C (5336KB)
BIT header sucessfully parsed.
Generating HPM header...
Device ID
                                  : 0×00
Manufacturer ID
                                : 0×0000000
Product ID
                                : 0×0000
                               : 0x54886D64
Time value
                    : 0x01
Component ID
Firmware revision
                                  : 0×0000
Firmware revision auxilary information
                                                 : 0×000000000
Generating header checksum
                                                 : 0×F0
Generating upgrade action checksum (prepare) : 0xFE
Generating upgrade action checksum (upload)
                                                   : ØxFD
Information: Output will be compressed with RLE
Reading 5464972 Bytes from file...
Largest RLE block is
Compression Ratio is
                                  : 128 bytes
                                  : 32.9%
16-bit Checksum of data is
                                  : 0×BDB3.
Begin of data stream is
                                : 9EFF810004BB1122004486FF04AA995566208100...
End of data stream is : 002081000220000002081000022000000.
Testing MD5 checksum : E5546C065678FBF39CE2CC5FC2F8F32A
Output data length is : 1796463 bytes
Overhead (header+MD5) size is : 99 bytes
                                  : llrf_ctrl_sis83001_acc1_r908.rle.hpm
Writing file
                                  : 1796463
Bytes actually written
All done.
```

Demonstration

```
PICMG HPM.1 Upgrade Agent 1.0.2:
-----Target Information-----
Device Id : 0x0
Device Revision : 0x80
Product Id : 0x0002
Manufacturer Id : 0x053f (Unknown (0x53F))
|ID | Name | Versions |
 | | Active| Backup|
| O | MMCV100 HPM| 2.00 | --.-- |
mskcpuhvf1@mskcpuhvf1:~$ ipmitool -H mskmchhvf1 -P "" -t 0x76 hpm upgrade SIS8300L2.hpm
PICMG HPM.1 Upgrade Agent 1.0.2:
Validating firmware image integrity...OK
Performing preparation stage...OK
Performing upgrade stage:
 ______
|ID | Name | Versions | Upload Progress | Upload Image |
           | Active| Backup| File | O% 50% 100% | Time | Size |
|---|--------|-----|-----|-----||-----||---+---+----||-----|
| O | MMCV100 HPM| 2.00 | --.-- | 0.01 ||.......|| 00.33 | 18cec |
```

Firmware upgrade procedure successful

show_sensorinfo

nat> show_sensorinfo 9 Sensor Information for FRU 9 / AMC5

| # | SDRType | Sensor I | ntity | Inst | Value | State | Nane |
|----|---------|----------|-------|------|---------|-------|----------------------|
| 0 | MDevLoc | | 0xc1 | 0x65 | | | SIS8300L2 AMC |
| 0 | Full | 0xf2 | 0xc1 | 0x65 | 0x01 | | Hot Sµap |
| 1 | Full | Voltage | 0xc1 | 0x65 | 12.1 V | ok | 12V PP |
| 2 | Full | Voltage | 0xc1 | 0x65 | 3.3D V | ok | 3.3V MP |
| 3 | Full | Voltage | 0xc1 | 0x65 | 0.97 V | ok | 1.0V CORE |
| 4 | Full | Voltage | 0xc1 | 0x65 | 2.48 V | ok | 2.5V |
| 5 | Full | Voltage | 0xc1 | 0x65 | 1.80 V | ok | 1.8V |
| 6 | Full | Voltage | 0xc1 | 0x65 | 1.49 V | ok | 1.5V DDR3 |
| 7 | Full | Current | 0xc1 | 0x65 | 0.240 A | ok | RTM PP Current |
| 8 | Full | Current | 0xc1 | 0x65 | 0.017 A | ok | RTM MP Current |
| 9 | Full | Тенр | 0xc1 | 0x65 | 35.5 C | ok | Inlet |
| 10 | Full | Тенр | 0xc1 | 0x65 | 39.5 C | ok | Out let |
| 11 | Full | Тенр | 0xc1 | 0x65 | 47.0 C | ok | Middle |
| 12 | Full | Тенр | 0xc1 | 0x65 | 40.0 C | ok | FPGA PCB |
| 13 | Full | Тенр | 0xc1 | 0x65 | 49.0 C | ok | FPGA DIE |
| 14 | Сонраст | OxOb | 0xc1 | 0x65 | 0x00 | | 0x00 FPGA Done |
| 15 | Сомраст | OxOb | 0xc1 | 0x65 | 0x00 | | OxOO FPGA Init |
| 16 | Сонраст | OxOb | 0xc1 | 0x65 | 0x00 | | OxOO RTM OC Fault |
| 17 | Сонраст | OxOb | 0xc1 | 0x65 | 0x00 | | 0x00 ID:0004A3D16829 |

nat> SEL: 1970/01/01 01:40:00 alive

Licensing

- Licensor needs so sign an NDA and a Software License Agreement
- Free of Charge for collaboration projects
- Licensing Items
 - Altium Designer Files as Templates for AMC and RTM
 - C Source Code
 - AMC FRU Generator
 - Command-Line HPM Generator

